

01-08-2003

**RECORD/**



102331733

**ENT APPLICATION**

11000 U.S. PTO  
10/331479  
12/31/02

12-31-02

NAME OF CONVEYING PARTY : Chih-Yung HUANG, Ting-Wei HUANG  
and Ching-Sung HSIAO

NAME OF RECEIVING PARTY : INDUSTRIAL TECHNOLOGY  
RESEARCH INSTITUTE

ADDRESS OF RECEIVING PARTY : 195 Chung Hsing Road, Sec. 4, Chutung,  
Hsinchu, Taiwan, R.O.C.

NATURE OF CONVEYANCE : Assignment of U.S. Patent Application

CONVEYANCE EXECUTION DATE : November 8, 2002

PATENT APPLICATION NO. : To be assigned

PATENT APPLICATION FILING DATE : December 31, 2002

APPLICATION FILED TOGETHER  
WITH THIS DOCUMENT : YES 10, 331479

APPLICATION EXECUTION DATE : November 8, 2002

CORRESPONDENCE : RABIN & BERDO, P.C.  
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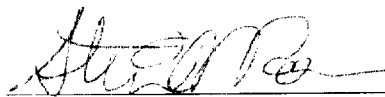
ATTORNEY REFERENCE : LOU 105

TOTAL NUMBER OF PATENTS  
AND APPLICATIONS INVOLVED : One

TOTAL FEE PAID : \$40.00

METHOD OF PAYMENT : ☒ Enclosed  
[ ] Authorized to be charged to  
deposit account

To the best of my knowledge and belief, the foregoing information is true and correct and  
any attached copy is a true copy of the original document.

  
Steven M. Rabin (Reg. No. 29,102)

December 31, 2002  
Date

Total number of pages including cover sheet, attachments and document: 2.

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**PATENT**  
**REEL: 013628 FRAME: 0453**

FREE ENCLOSURE 942  
Please charge any further  
fee to our Deposit Account  
No. 19-0012

# ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) Chih-Yung HUANG  
 Full Name(s) Ting-Wei HUANG  
Ching-Sung HSIAO

Hereby sell, assign and transfer to

Assignee INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE  
 Name and Address No. 195, Chung Hsing Road, Sec. 4, Chutung,  
Hinchu, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

⇒ MICROWAVE PLASMA PROCESSING APPARATUS  
 Title of Invention: \_\_\_\_\_

Which application was

Complete either a) executed by the undersigned on 11-8-2002  
 b) filed on the \_\_\_\_\_  
 Serial No. \_\_\_\_\_

Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date Signed at HSINCHU, TAIWAN, R.O.C.  
 On Nov. 08, 2002

Inventor(s) Chih-Yung Huang, Nov. 08, 2002 Chih-Yung HUANG  
 Full Signature(s) Ting-Wei Huang, Nov. 08, 2002 Ting-Wei HUANG  
Ching-Sung Hsiao, Nov. 08, 2002 Ching-Sung HSIAO